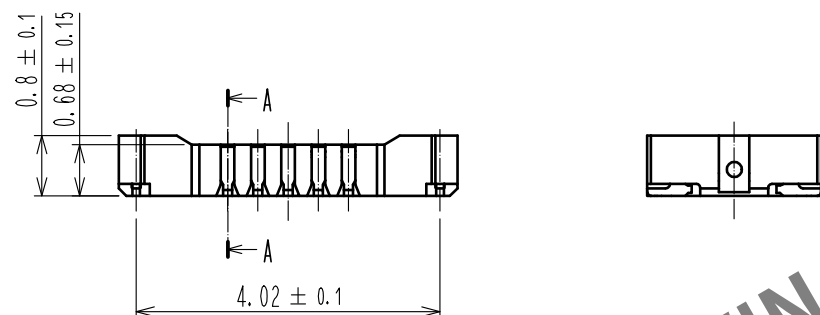




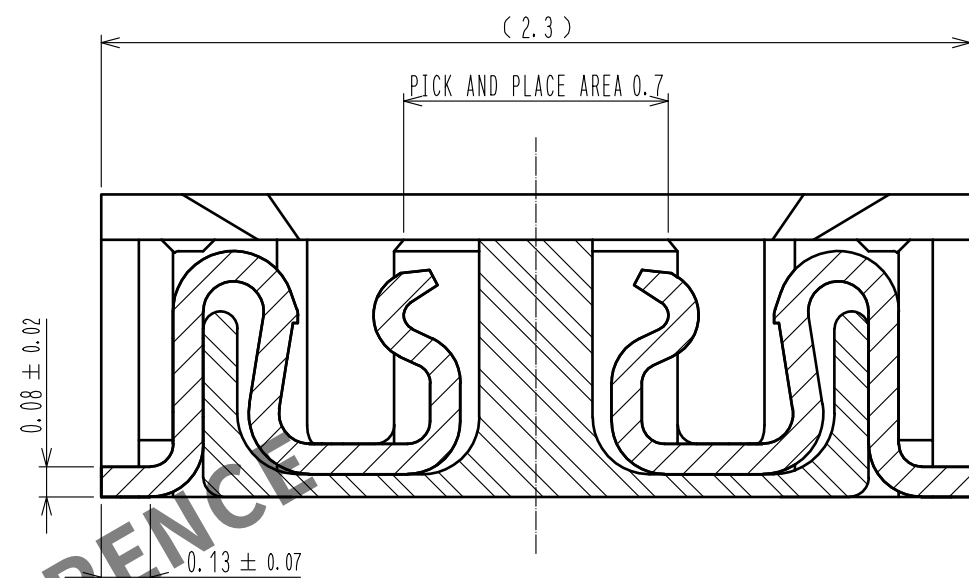
NOTE 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX

2. CONTACT PLATING SPECIFICATIONS
CONTACT AREA : GOLD 0.05 μm MIN
SMT LEAD : GOLD 0.05 μm MIN
UNDERPLATING : NICKEL 1 μm MIN
(SURFACE : SEALING)

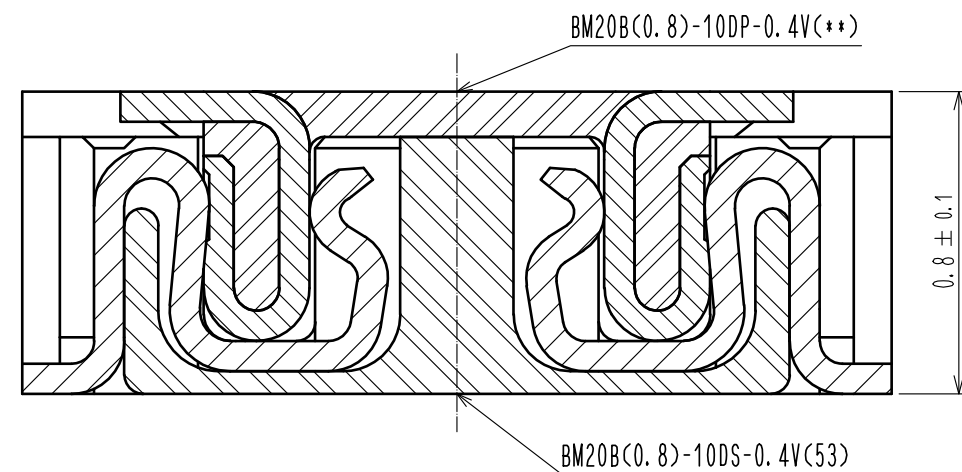
3. METAL FITTING PLATING SPECIFICATIONS
SMT LEAD : GOLD 0.05 μm MIN
UNDERPLATING : NICKEL 1 μm MIN
(SURFACE : SEALING)

4. HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.

5. GATE POSITION IS INDICATED IN APPROX POSITION SHOWN.



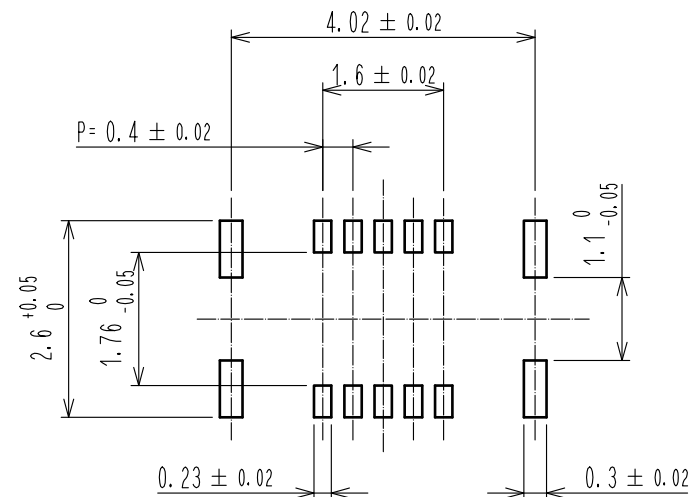
ENGAGEMENT FIGURE (50:1)



4	PS	CLEAR (EMBOSSED CARRIER TAPE)				
3	BRASS			7	PS	CLEAR (REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE			6	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK		5	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH . REMARKS		NO.	MATERIAL	FINISH . REMARKS

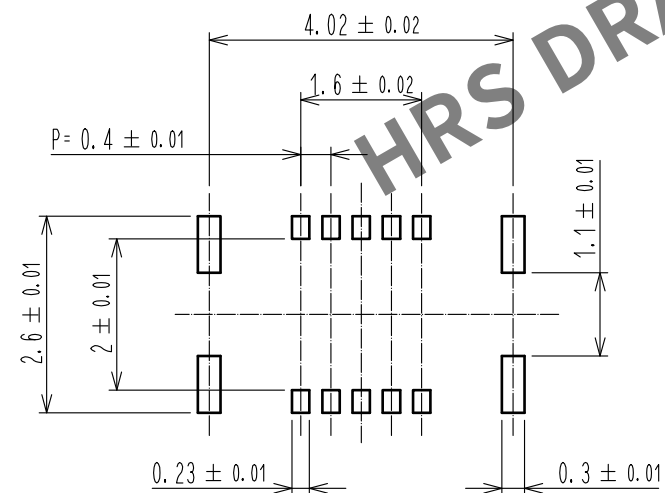
UNITS mm		SCALE 10 : 1		COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
HIROSE ELECTRIC CO., LTD.	APPROVED :MO. ISHIDA		15. 10. 17		DRAWING NO.	EDC-332314-53-01		
	CHECKED :TS. MIYAZAKI		15. 10. 17		PART NO.	BM20B(0.8)-10DS-0.4V(53)		
	DESIGNED :RT. SHIMIZU		15. 10. 16		CODE NO.	CL684-9008-4-53		
	DRAWN :KR. AJITO		15. 10. 16					

◆RECOMMENDED PCB LAYOUT

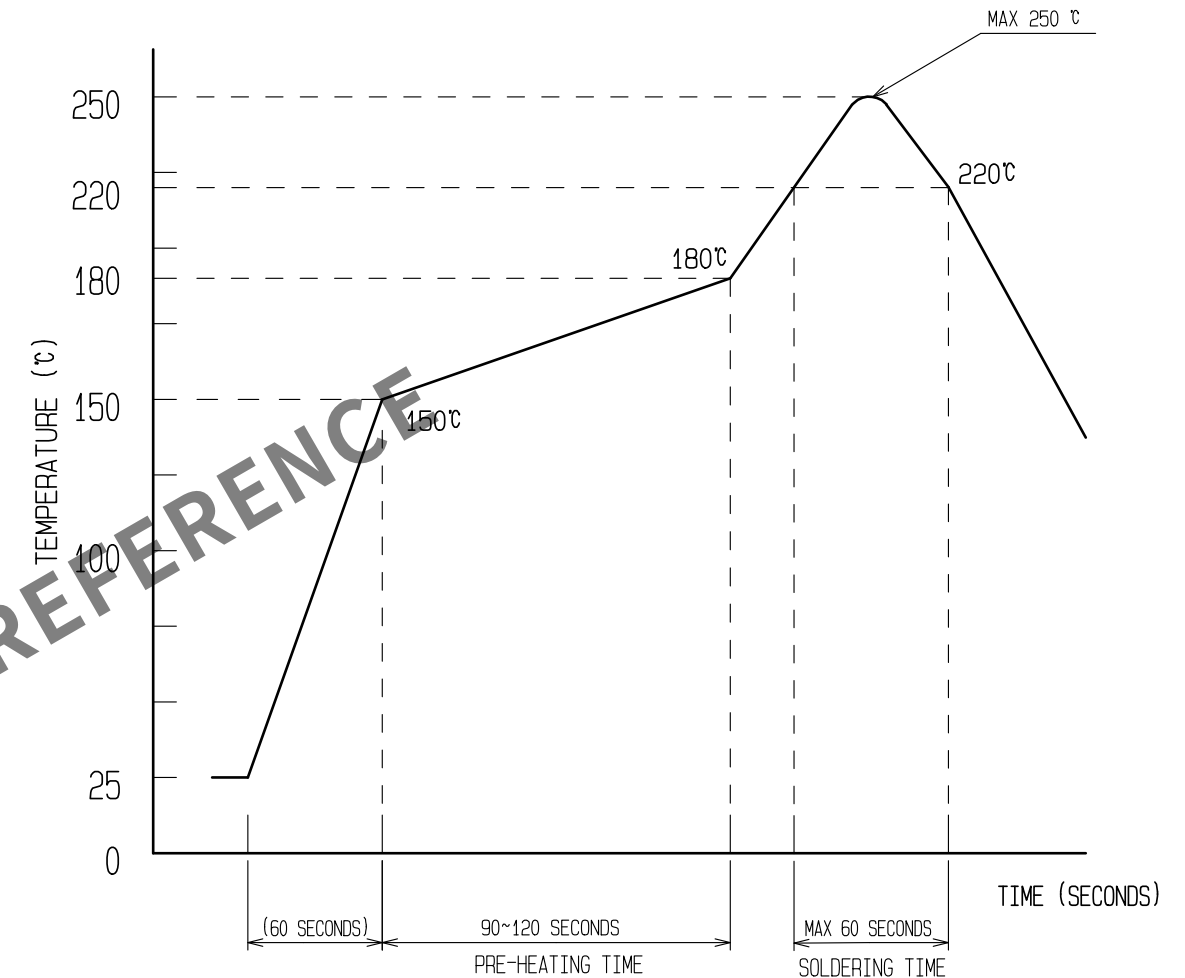


◆RECOMMENDED METAL MASK DIMENSIONS

MATAL MASK THICKNESS : $100 \mu\text{m}$



6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



- REFLOW METHOD : IR REFLOW
NUMBER OF REFLOW CYCLES : 2 CYCLES MAX.
- 1) REFLOW TIME
DURATION ABOVE 220°C, 60 SEC MAX.
(PEAK TEMPERATURE : 250°C MAX)
 - 2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: 90-120 SEC.

6 THE TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND
OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE,
A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED
PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS

DRAWING NO.	EDC-332314-53-01
PART NO.	BM20B(0.8)-10DS-0.4V(53)
CODE NO.	CL684-9008-4-53

2/3

